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(54) **RESISTIVE MEMORY ELEMENT SENSING USING AVERAGING**

6,317,375 B1 * 11/2001 Perner 365/189.11

* cited by examiner

(75) Inventor: **R. J. Baker**, Meridian, ID (US)

Primary Examiner—Richard Elms

(73) Assignee: **Micron Technology, Inc.**, Boise, ID (US)

Assistant Examiner—VanThu Nguyen

(74) *Attorney, Agent, or Firm*—Dickstein Shapiro Morin & Oshinsky LLP

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(57) **ABSTRACT**

A system for determining the logic state of a resistive memory cell element, for example an MRAM resistive cell element. The system includes a controlled voltage supply, an electronic charge reservoir, a current source, and a pulse counter. The controlled voltage supply is connected to the resistive memory cell element to maintain a constant voltage across the resistive element. The charge reservoir is connected to the voltage supply to provide a current through the resistive element. The current source is connected to the charge reservoir to repeatedly supply a pulse of current to recharge the reservoir upon depletion of electronic charge from the reservoir, and the pulse counter provides a count of the number of pulses supplied by the current source over a predetermined time. The count represents a logic state of the memory cell element.

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(58) **Field of Search** 365/148, 100, 365/158, 189.01, 189.07, 189.09, 209, 233, 236

(56) **References Cited**

U.S. PATENT DOCUMENTS

6,038,166 A * 3/2000 Wong 365/185.03
6,188,615 B1 * 2/2001 Perner et al. 365/100

24 Claims, 6 Drawing Sheets

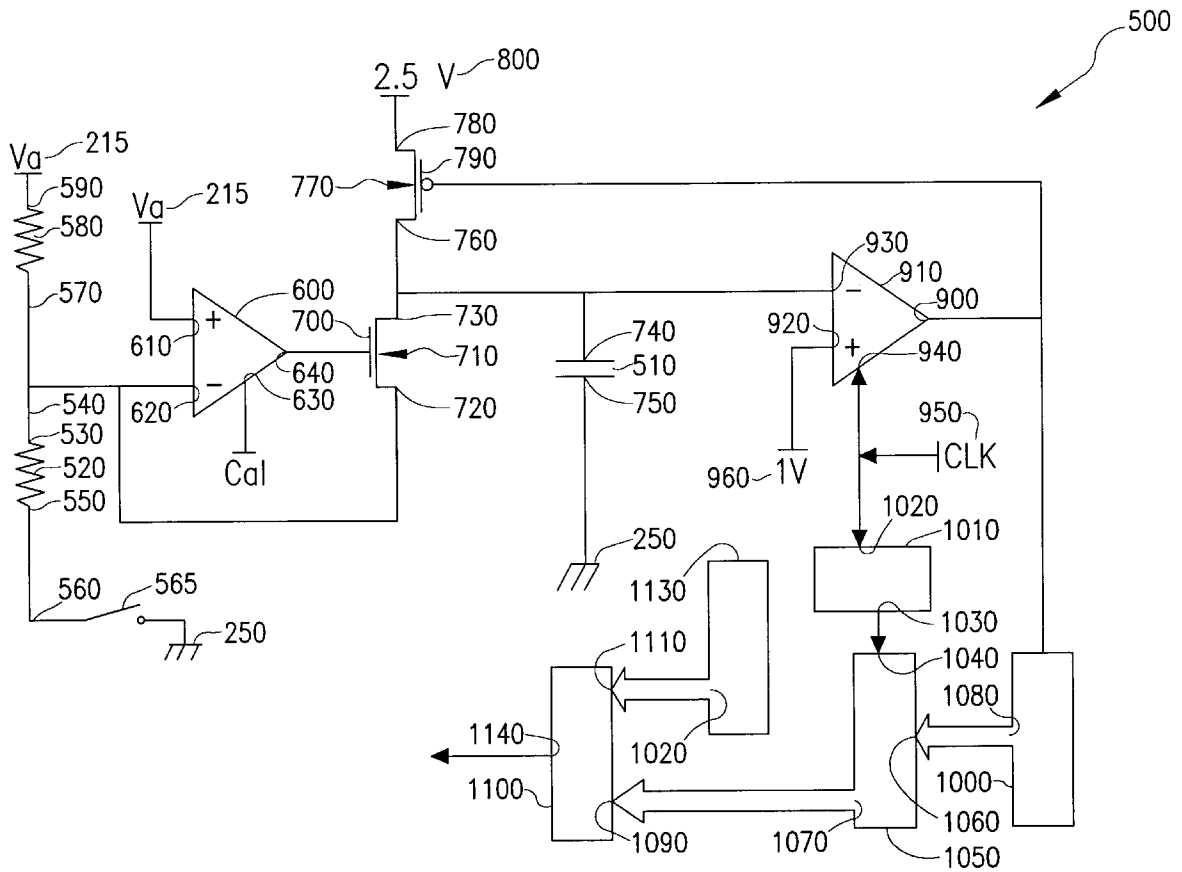
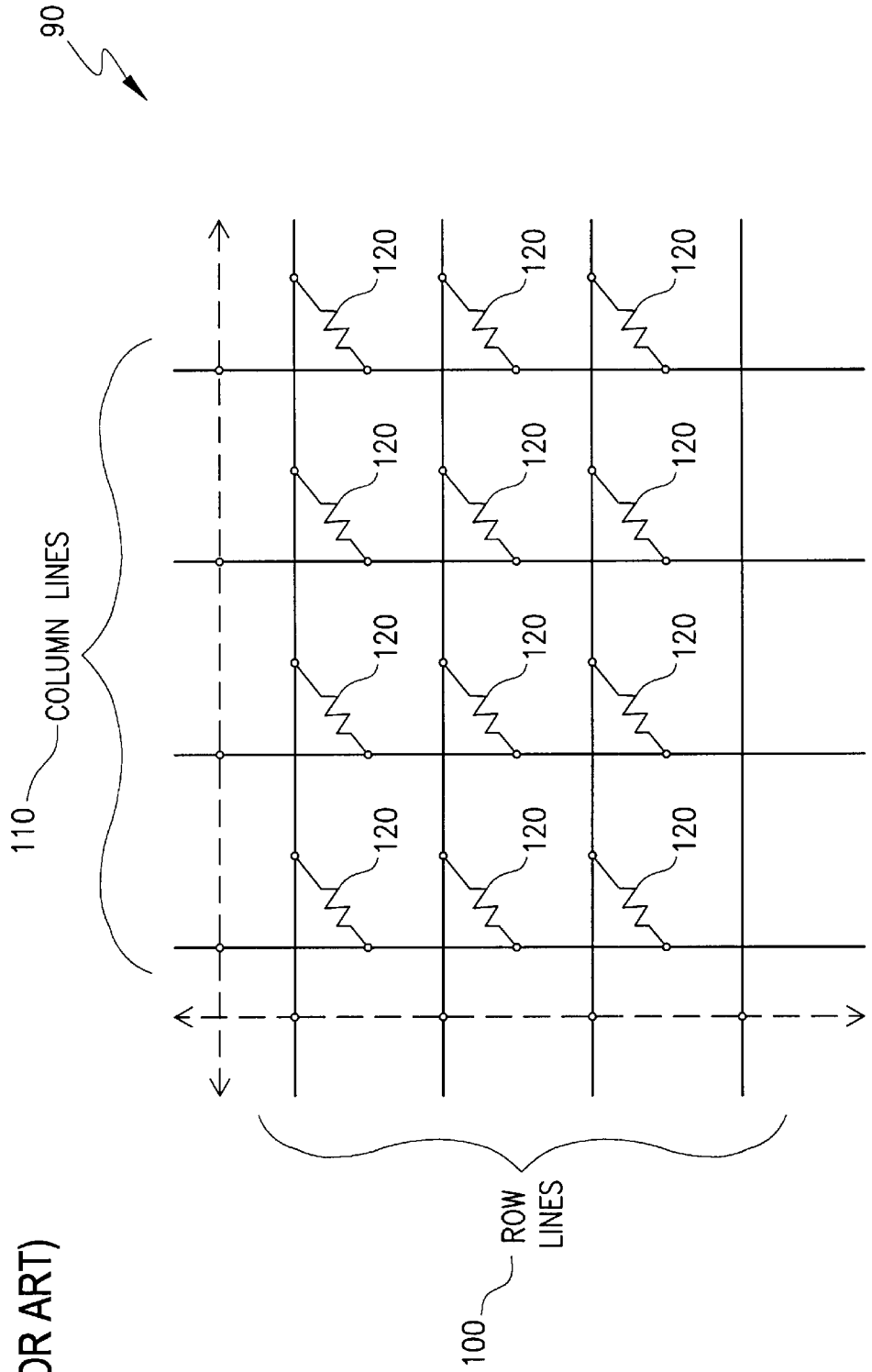


FIG. 1
(PRIOR ART)



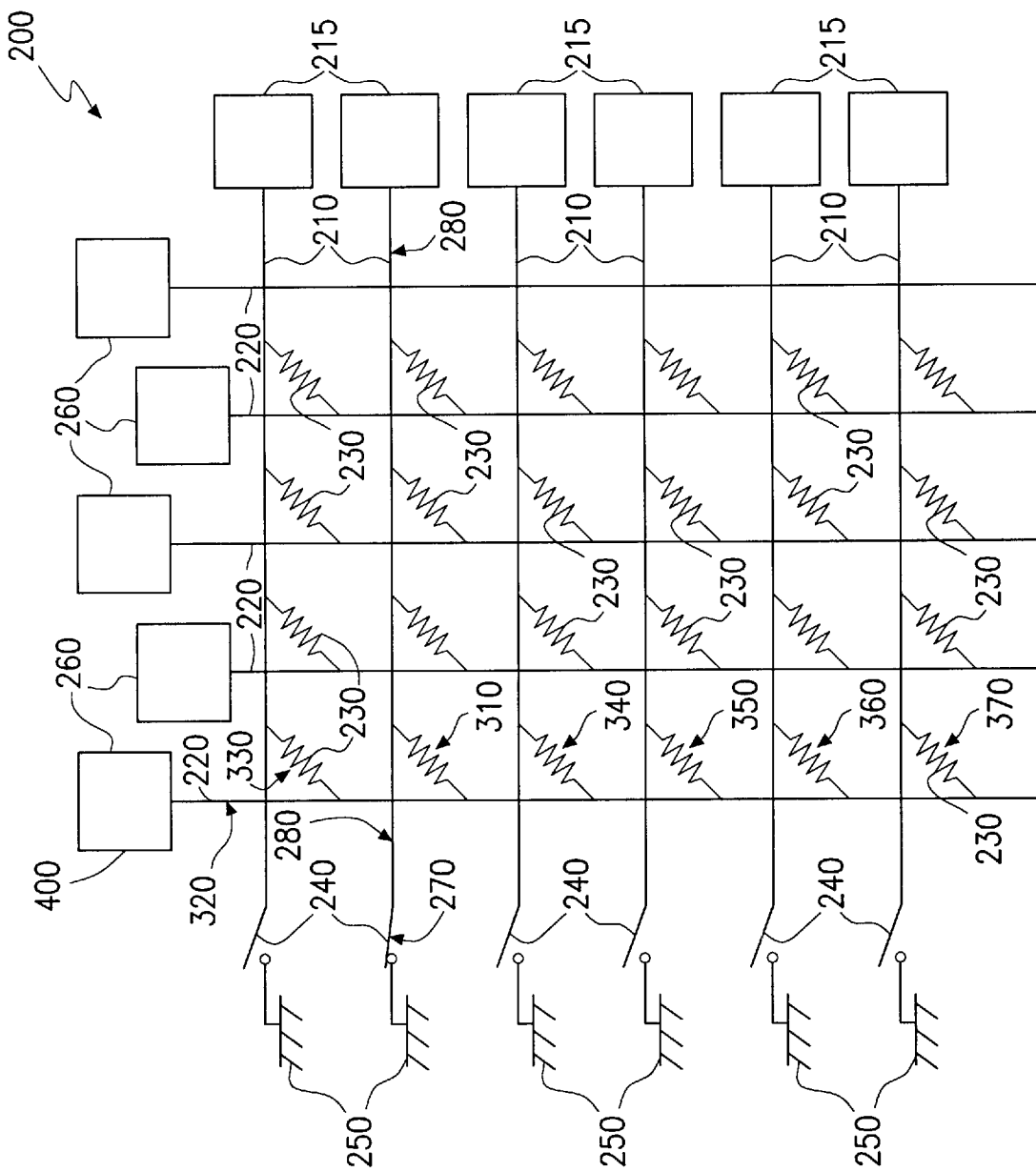


FIG. 2

FIG. 3

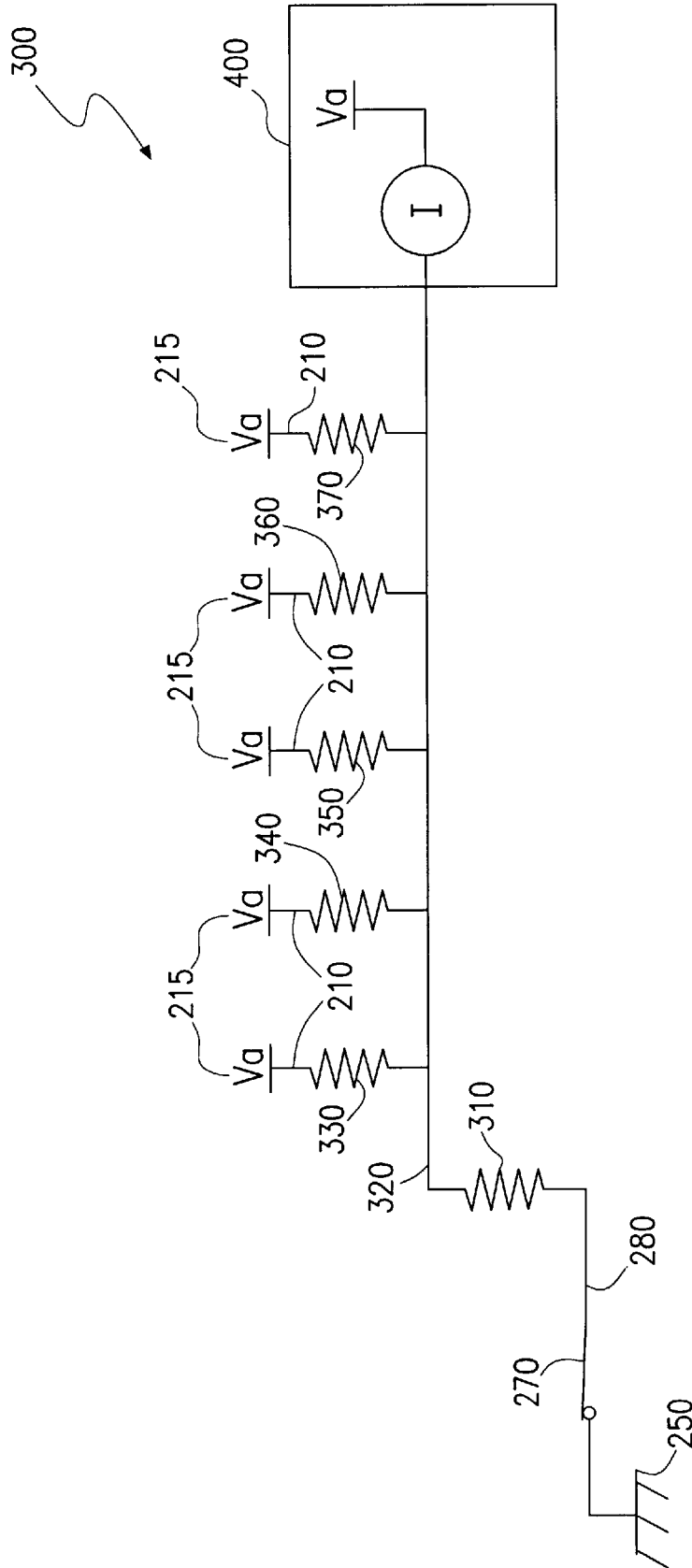


FIG. 4

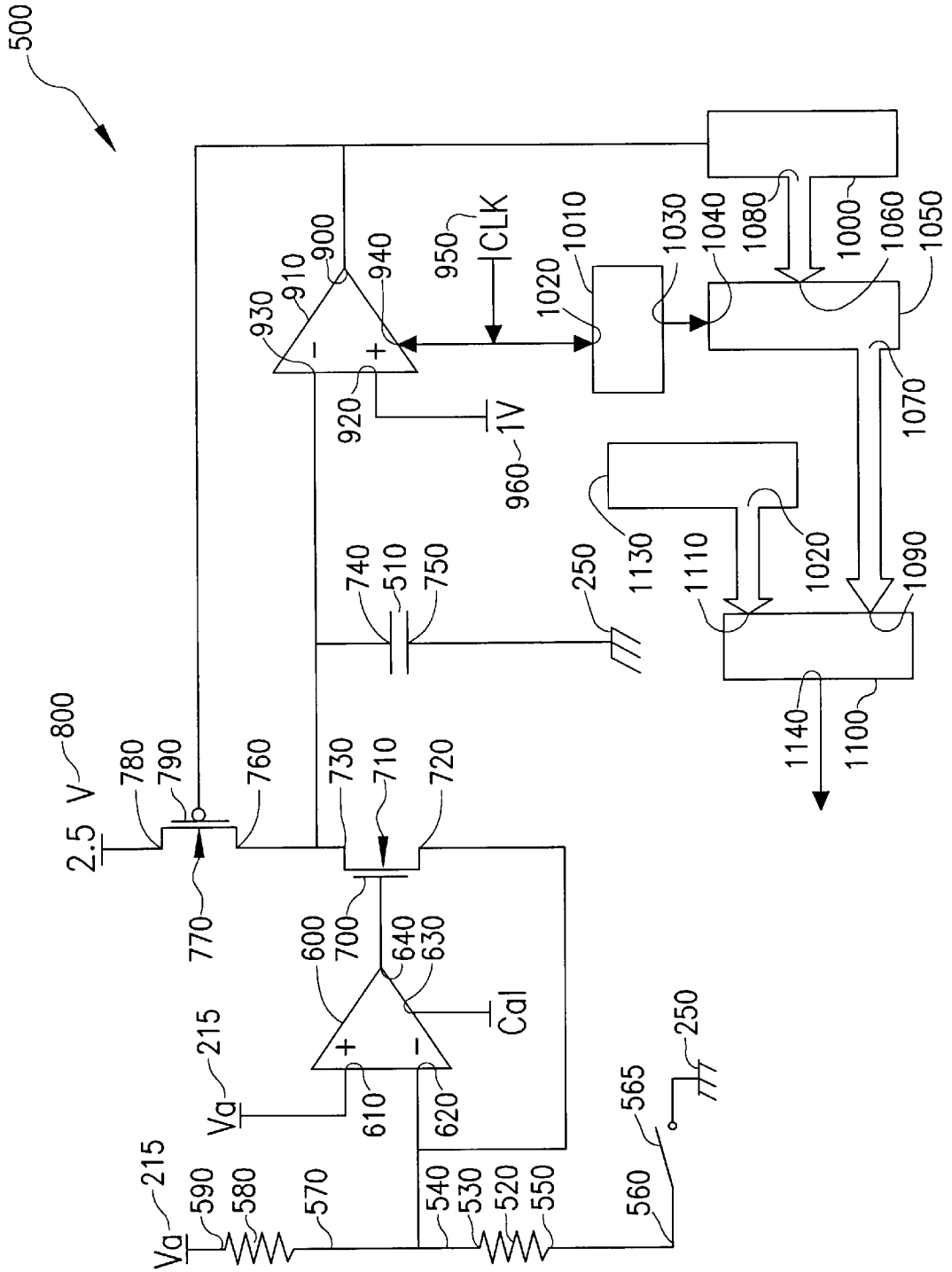


FIG. 5

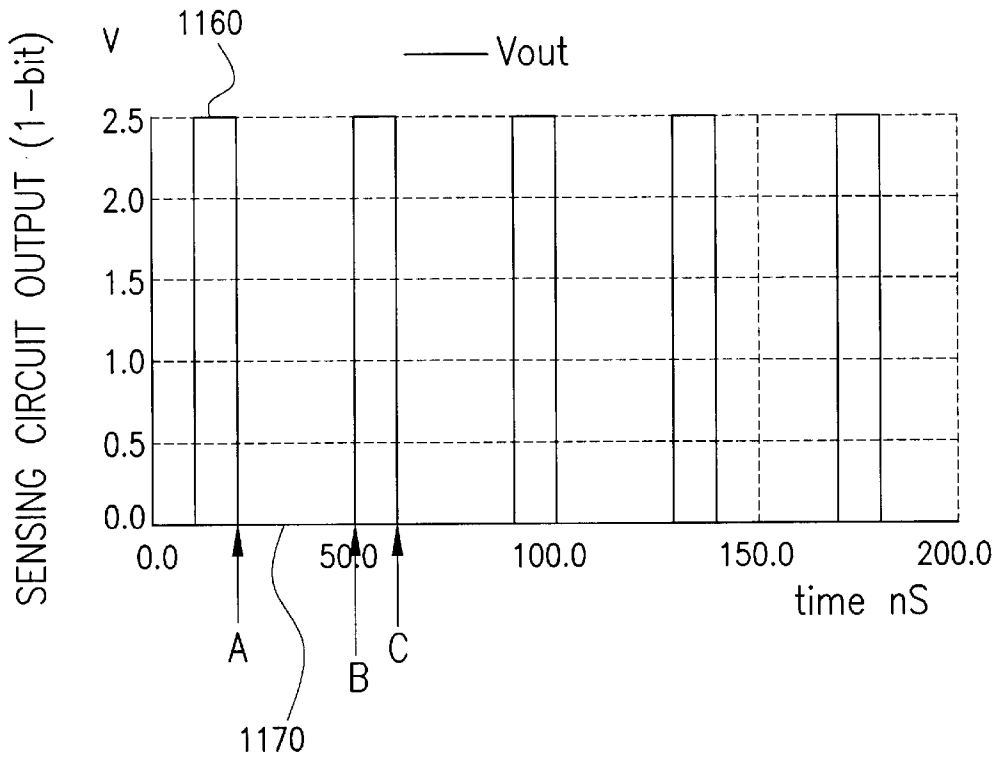


FIG. 6

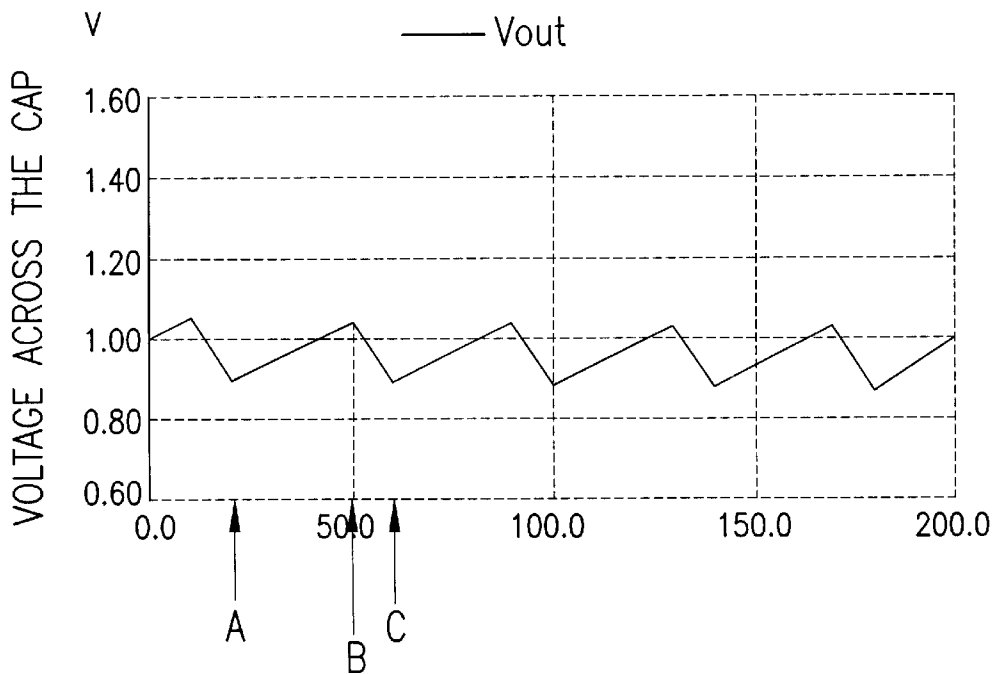
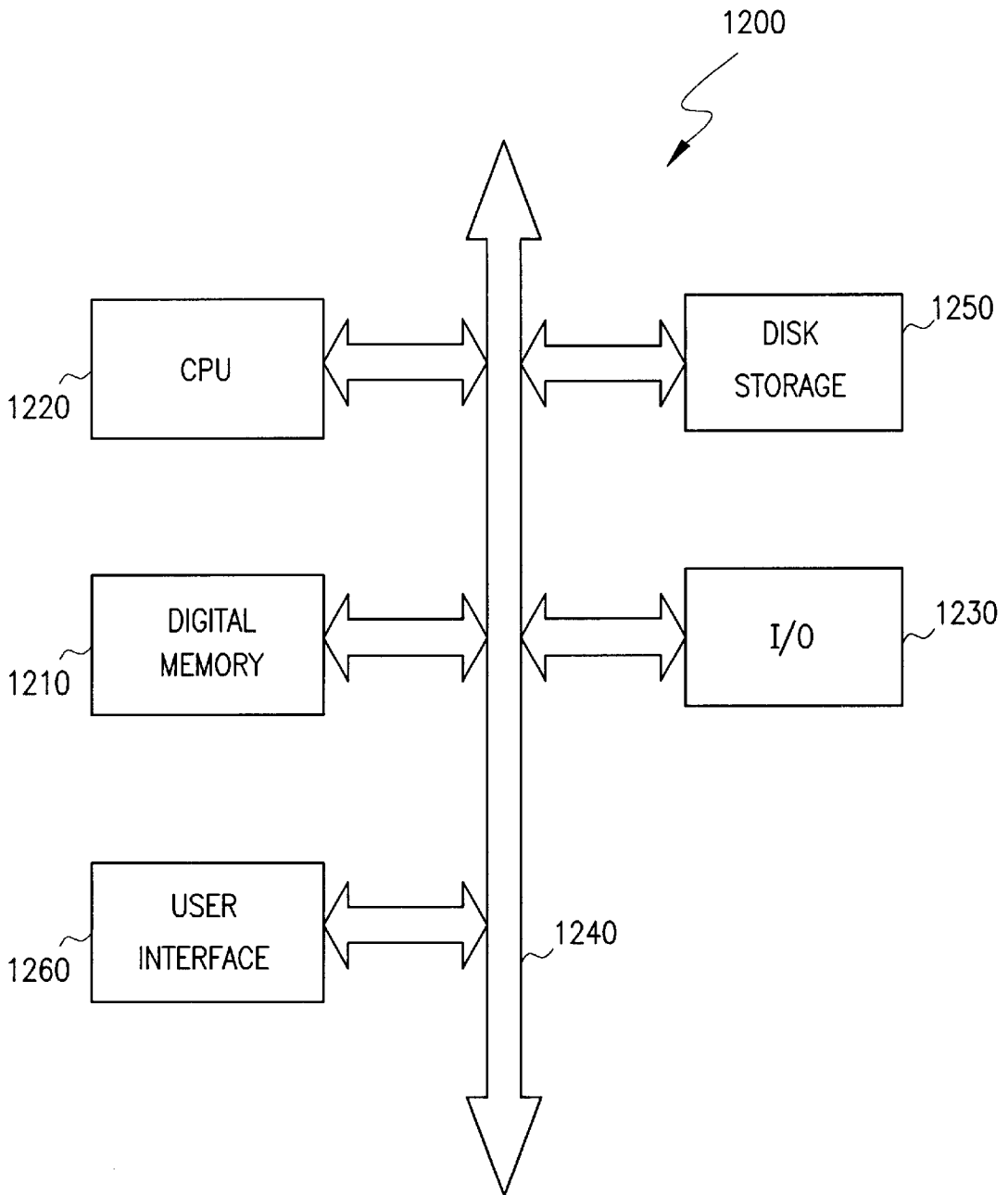


FIG. 7



RESISTIVE MEMORY ELEMENT SENSING USING AVERAGING

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to the field of resistor-based memory circuits. More particularly, it relates to a method for precisely sensing the resistance value of a resistor-based memory cell, for example, an MRAM magnetic memory cell.

2. Description of the Related Art

FIG. 1 shows one example of a resistor based memory. The memory includes a memory cell array **90** having a plurality of row lines **100** arranged in normal orientation to a plurality of column lines **110**. Each row line is connected to each of the column lines by a respective of resistor **120**.

A magnetic random access memory (MRAM) is one approach to implementing a resistor based memory. In an MRAM, each resistive memory cell includes a magnetizable film. The resistance of the cell varies, depending on the magnetization state of the film. Logical data can be stored by magnetizing the film of particular cells so as to represent the logic states of the data. The stored data can be read by measuring the resistance of the cells, and interpreting the resistance values measured as logic states. Making the required resistance measurements, however, is problematic.

In a resistance memory, one resistance value, e.g., a higher value, may be used to signify a logic "HIGH" while another resistance value, e.g., a lower value, may be used to signify a logic "LOW." The stored logic state can be detected by measuring the memory cell resistance using Ohm's law. For example, resistance is determined by holding voltage constant across a resistor and measuring, directly or indirectly, the current that flows through the resistor. Note that, for MRAM sensing purposes, the absolute magnitude of resistance need not be known; only whether the resistance is above or below a value that is intermediate to the logic high and logic low values.

Sensing the logic state of an MRAM memory element is difficult because the technology of the MRAM device imposes multiple constraints. In a typical MRAM device an element in a high resistance state has a resistance of about 1 M Ω . An element in a low resistance state has a resistance of about 950 K Ω . The differential resistance between a logic one and a logic zero is thus about 50 K Ω , or 5% of scale.

Accordingly, there is a need for a simplified resistance measuring circuit able to repeatably and rapidly distinguish resistance values varying by less than 5% on a one M Ω scale.

BRIEF SUMMARY OF THE INVENTION

The invention provides a method and apparatus for measuring the resistance of a resistive memory element. The resistance is measured by charging a capacitor, allowing the capacitor to discharge through a selected resistive memory element while maintaining a substantially constant voltage across the resistive memory element, sensing the charge remaining on the capacitor, repeatedly recharging the capacitor with a pulse of definite charge each time the capacitor voltage drops to a predetermined value, and determining a time average current into the capacitor based on a duty cycle of the recharging pulses. Knowledge of the time average current into the capacitor, yields the current flowing into the resistor since the current flowing into the capacitor

must equal the current flowing out of the capacitor and into the resistor. One can measure or set the voltage across the resistive memory element and determine the resistance of the element from the current through the element and the voltage across it.

In various aspects of the invention, the actual resistance of the memory element is not calculated. Instead, the number of capacitor charging pulses is counted, and the numerical count thus acquired is compared to a reference count value. The reference value is chosen to lie between count values representing logical one and logical zero. Therefore a count value greater than the reference indicates one logical state, and a count value less than the reference value indicates another. In a further aspect of the invention, more than one reference value is established, and a memory element capable of exhibiting more than two resistance values is used. Consequently the memory element may store more than two logical values. The logical values are determined based on the relationship between the count value counted and the standard values used to establish thresholds between logical values.

In a further aspect, the apparatus and method of the invention may be used to measure the resistance or impedance of any resistive or impedance device.

These and other aspects and features of the invention will be more clearly understood from the following detailed description which is provided in conjunction with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 shows a conventional magnetic random access memory array in schematic form.

FIG. 2 shows a magnetic random access memory device according to one aspect of the present invention in schematic form, including resistance sensing circuits;

FIG. 3 shows a portion of a magnetic random access memory device according to one aspect of the invention including a sensing circuit and sneak resistance;

FIG. 4 shows a circuit for sensing resistance using averaging according to one aspect of the present invention;

FIG. 5 shows a graphical representation of sensing circuit digital output over time according to one aspect of the present invention;

FIG. 6 shows a graphical representation of voltage across a capacitor over time according to one aspect of the present invention;

FIG. 7 shows a computer system incorporating a digital memory according to one aspect of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

FIG. 2 shows a portion of a resistive memory device according to the invention. The device includes an array **200** of Magnetic Random Access Memory (MRAM) elements, a plurality of electrically conductive row lines **210**, and a plurality of electrically conductive column lines **220**. Each row line is connected to each of the plurality of column lines by a respective MRAM resistive element **230**. A plurality of switches **240**, typically implemented as transistors, are each switchingly connected between one of the row lines and a first source of constant potential (ground) **250**. A plurality of sensing circuits **260**, are respectively connected to the plurality of column lines **220**. Each sensing circuit **260** includes a source of constant electrical potential (V_A) which is applied to the respective column line. A plurality of pull-up

voltage sources **215**, supplying voltage V_A , are respectively connected to each of the plurality of row lines **210**.

In operation, an exemplary switch **240**, such as switch **270** associated with a particular row line **280**, is closed so as to bring that row line to ground potential and a particular column line, e.g., **320** is sensed to read the resistance value of a particular resistor **310**.

FIG. **3**, shows the resulting electrical circuit for the relevant portion **300** of the memory array when row **280** is grounded. As shown, memory element **310** to be sensed is connected between a grounded row line **280** and a particular column line **320**. Also connected to the column line **320** are a plurality of other resistive memory elements (e.g. elements **330**, **340**, **350**, **360**, **370**) each of which is connected at its opposite end to a pull-up voltage source V_A **215** through a respective row line **210**. In addition, a respective sensing circuit **400** is connected to the column line **320**. The sensing circuit **400** includes a voltage supply that maintains the column line **320** at electrical potential V_A .

The other resistive memory elements (those tied to ungrounded row lines) **330**, **340**, **350**, **360**, **370**, form an equivalent resistance referred to as sneak resistance. The effective resistance of the sneak resistance is small. A typical value for sneak resistance might be 1 K Ω . Nevertheless, because both ends of each ungrounded resistor are ideally maintained at the same potential (here V_A) as the column line **320**, net current flow through the sneak resistance is desirably nearly zero.

In contrast, a measurable current flows through the grounded resistor memory element **310**. This measurable current allows evaluation of the resistance of the memory element **310** by the sensing circuit **400**.

One proposal for sensing the resistance value of a memory cell is to charge a capacitor to a predetermined first voltage and then discharge the capacitor through the memory cell resistance until it holds a second lower predetermined voltage. The time taken for the capacitor to discharge from the first to the second voltage is a measure of cell resistance. A problem with this approach is that since the resistance values representing the different logic states of a cell are very close in value (only 5% difference) it is difficult to obtain an accurate and reliable resistance measurement, even if digital counting techniques are employed to measure the discharge time of the capacitor.

Thus, even when using digital counting techniques, the discharge time of the capacitor must be counted quite precisely to sense the different resistance values and distinguish logic states. To achieve this precision, either the counting clock must be operated at a high frequency or the capacitor must be discharged relatively slowly. Neither of these options is desirable, since slow capacitor discharge means slow reading of stored memory values, and a high clock frequency requires high frequency components. In either case, a counter having a large number of stages is also required.

The present invention provides a resistive measuring circuit and operating method which rapidly ascertains a resistive value without storing large data counts, and without requiring highly precisioned components.

FIG. **4** illustrates an exemplary embodiment of a resistance sensing circuit **500** constructed in accordance with the invention. Sensing circuit **500** relies on the cyclical discharge of a capacitor **510** to determine the value of a memory cell resistance **520**. The duty cycle of a recharging signal for the capacitor **510** represents a value of resistance

The resistance measuring circuit **500** outputs a bit stream from an output **900** of a comparator **910**. The ratio of logic one bits to a total number of bits (or, in and other aspect of the invention, the ratio of logic one bits to logic zero bits) in the bit stream yields a numerical value. This numerical value corresponds to the current that flows through the resistance **520** in response to a known applied voltage. For example, assume that a current source can deliver current at two discrete current levels, corresponding to two different states of a logical input signal. When the signal is in logic one state, the source delivers, for example, 2 μA . When the signal is in a logic zero state, the source delivers, for example, 0 μA . The logical input signal is monitored over a finite time span corresponding to a number of bit-length time periods. Over that time span, the number of logic one and logic zero bits are recorded. By straightforward algebra, the average current delivered by the current source over the corresponding time span may be calculated as follows:

$$I_{AVG} = \frac{(\text{number of logic 1 bits}) * 2\mu\text{A} + (\text{number of logic 0 bits}) * 0\mu\text{A}}{\text{total number of bits in the signal}}$$

As an example, if, over a time span corresponding to 4 cycles, there is one logic one bit and three logic zero bits then the average current over the four cycles is 0.5 μA .

$$I_{AVG} = \frac{1 * 2\mu\text{A} + 3 * 0\mu\text{A}}{4} = 0.5\mu\text{A}$$

The operation of the FIG. **4** sensing circuit is now described in greater detail. An MRAM resistive memory element **520** to be sensed has a first end **530** connected to a column line **540** and a second end **550** connected to ground **250** through a row line **560** and switch **565**. Also connected to the column line **540** is a first end **570** of a sneak resistance **580**. The sneak resistance has a second end **590** connected to a source of constant potential V_A **215**. The sneak resistance **580** represents a plurality of MRAM resistive elements associated with the particular column line **540** and with a respective plurality of unselected row lines, as described above with reference to FIG. **3**.

A first operational amplifier (op-amp) integrator **600** is provided which has a non-inverting (positive) input **610**, an inverting (negative) input **620**, a calibrate offset input **630**, and an output **640**. The output **640** of the first op-amp **600** is connected to a control input (gate) **700** of a first transistor **710**, which in this exemplary embodiment is an N-channel transistor.

The first transistor **710** includes a drain **720** connected to both the selected column line **540** and the inverting input **620** of the first op-amp **600**. The first transistor also includes a source **730** operatively connected to a first terminal **740** of a capacitor **510**. The capacitor **510** includes a second terminal **750** operatively connected to a ground potential **250**. The source **730** of the first transistor **710** is also connected to a drain **760** of a second transistor **770**. In this exemplary embodiment, this second transistor **770** is a PMOS transistor. The second transistor **770** includes a source **780** and a gate **790**, in addition to the drain **760**. The source **780** is operatively connected to a supply voltage **800**, which in this exemplary embodiment is 2.5 volts. The gate **790** is operatively connected to an output **900** of a clocked comparator **910**. The clocked comparator **910**, shown as a clocked second operational amplifier, includes the output **900**, a non-inverting (positive) input **920**, an inverting (negative)

input **930**, and a clock input **940** connected to a source of a clock signal **950**. The comparator **910** may be implemented as a simple clocked latch, or the comparator **910** may be simply enabled by the clock CLK signal.

The output **900** of the second op-amp is also connected to a counter **1000** which counts the rising transitions at the comparator output **900**. The non-inverting input **920** of the second op-amp **910** is connected to a source of a reference voltage **960** (1 volt in the exemplary embodiment shown).

A second counter **1010** counts the total number of transitions of the clock **950** during a measuring cycle. This counter **1010** includes an input **1020** for receiving clock signal **950** and at output **1030** that exhibits a signal when counter **1010** reaches a predetermined count. The output **1030** is connected to a latch input **1040** of a latching buffer **1050**. The latching buffer **1050** includes a data input **1060** and data output **1070**. The data input **1060** is connected to a data output **1080** of the first counter **1000**. The data output **1070** is connected to a first data input **1090** of a digital comparator **1100**. The digital comparator **1100** includes a second data input **1110** connected to a data output **1120** of a source of a reference value **1130**. In one embodiment, the source of the reference value **1130** is a buffer or other device holding a digital number.

The sensing circuit **500** operates in the following manner when activated when a row line is grounded and a resistance value is to be sensed. Capacitor **510** is initially discharged, resulting in a negative output signal on the output **900** of the second op-amp **910**. This causes the second transistor **770** to be placed in a conductive state, permitting capacitor **510** to begin charging. When the voltage on capacitor **510** equals that applied to the non-inverting input **920** of the second op-amp **910** (here 1 volt), the output **900** of the second op-amp changes state to a positive value at the next transition of the clock **950**. This turns off the second transistor **770**. The charge stored on capacitor **510** is discharged through the first transistor **710** and cell resistance **520** under the control of the first op-amp **600**. The first op-amp **600** tries to maintain a constant voltage VA on the selected column line **540**.

As charge is depleted from capacitor **510** the voltage on the capacitor drops until it falls below the voltage (1 volt) applied to the reference input **920** of the clocked comparator **910**. After this threshold is passed, the next positive clock transition applied to the clock input **940** causes the output of comparator **910** to go low again turning on the second transistor **770** and causing current to begin flowing through the second transistor **770** to recharge capacitor **510**.

In one embodiment, the capacitor **510** is recharged during one clock cycle of clock source **950**, so the comparator output **900** switches to high and the second transistor **770** is shut off again at the next positive dock transition. Transistor **770** is sized to allow a substantially constant current (e.g., 2.5 μ A) to flow to capacitor **510** when transistor **770** is in a conductive state.

The described charging and discharging of capacitor **510** under the control of the first **710** and second **770** transistors occurs repeatedly during one sense cycle. Each time the output of the comparator **910** goes low, a current pulse is allowed to pass through the second transistor **770** and the first counter **1000** incremented. Each time the clock signal **950** transitions positive, the second counter **1010** is incremented. When the second counter **1010** reaches a preset value, it triggers the latch **1050**, which latches that number of pulses counted by the first counter **1000** during the sensing period. The number of pulses counted is latched onto the data output **1070** (and data input **1090**). The

comparator **1100** then evaluates the values presented at the first and second data inputs **1090**, **1110**, and ascertains whether the value at the first data input **1090** is larger or smaller than the reference value at the second data input **1110**. The reference value at input **1110** is set between two count values which correspond to "hi" and "low" resistance states for resistor **520**. Thus if the value of the first data input **1090** is larger than the reference value, then a first logical value (e.g. logic one) is output on an output **1140** of the digital comparator **1100**. If the value of the first data input **1090** is smaller than the reference value, then a second logical value (e.g. logic zero) is output on the output **1140** of the digital comparator **1100**. In a variation, a comparator **1100** capable of comparing the digital value applied at the data input **1090** to a plurality of reference values **1110** can distinguish a value stored in a single resistive memory element as between multiple resistance values. In a further variation, the capacitor **510** is pre-charged prior to a measuring cycle. By pre-charging the capacitor **510**, the number of cycles of the clock signal **950** required to measure the state of the memory element is reduced. In another variation the capacitor is not pre-charged, in which case sensing the resistance of the memory element takes longer, but the circuitry and/or process is simplified.

FIGS. **5** and **6** show an exemplary relationship between the output signal produced at output **900** of the clocked comparator **910** and the voltage on capacitor **510** over time. FIG. **5** shows the output signal produced by the clocked comparator when a 100 MHz clock signal is applied to the clock input **940**. At a clock frequency of 100 MHz, clock pulses are spaced at an interval of 10 ns. In the example shown, the output of the clocked comparator is high **1160** for one clock pulse (10 ns) and low **1170** for three clock pulses (30 ns). This corresponds to the voltage waveform shown in FIG. **6**. In FIG. **6**, the voltage of the capacitor **510** is shown to begin rising when the output **900** of the clocked comparator goes low (time A), thereby turning on the PMOS transistor **770**. The voltage rises for 30 ns, or three clock pulses until time B. At time B, the output of the clocked comparator goes high again, turning off the PMOS transistor. The voltage on the capacitor **510** then begins to drop again while the PMOS device remains off for one clock pulse, or 10 ns (until time C). Accordingly, in the example shown, the duty cycle of the signal output by the clocked comparator **910** is 75% (three on-pulses for every off-pulse).

FIG. **9** shows a computer system **1200** including a digital memory **1210** having a resistance measuring memory cell sensor according to the invention. The computer **1200**, as shown includes a central processing unit (CPU) **1220**, for example, a microprocessor, that communicates with one or more input/output (I/O) devices **1230** over a bus **1240**. The computer system also includes peripheral devices such as disk storage **1250** and a user interface **1260**. It may be desirable to integrate the processor and memory on a single IC chip.

While preferred embodiments of the invention have been described and illustrated above, it should be understood that these are exemplary of the invention and are not to be considered as limiting. Additions, deletions, substitutions, and other modifications can be made without departing from the spirit or scope of the present invention. Accordingly, the invention is not to be considered as limited by the foregoing description but is only limited by the scope of the appended claims.

What is claimed is:

1. A method of measuring the resistance of a memory element comprising:

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producing a plurality of electrical pulses at a rate related to said memory element resistance;
 counting said electrical pulses over a predetermined time period to produce a pulse count; and
 evaluating said pulse count to determine said resistance.

2. The method according to claim 1 wherein each said electrical pulse comprises a pulse of substantially uniform width.

3. The method according to claim 1 wherein said evaluating comprises comparing said pulse count to a reference pulse count to determine said memory element resistance.

4. The method according to claim 3 wherein said evaluating further comprises determining said memory element resistance as one value if said pulse count is above said reference pulse count and as another value if said pulse count is below said reference pulse count.

5. The method for sensing a resistance of a resistor comprising:
 charging a capacitor to a voltage level;
 discharging said capacitor through said resistor;
 generating at least one recharging pulse each time the voltage on the capacitor falls below a predetermined value;
 using said recharging pulse to recharge the voltage on said capacitor; and
 determining said resistance from the number of recharging pulses which are generated during a predetermined period of time.

6. The method as defined in claim 5 wherein said discharging includes discharging said capacitor through said resistor at a substantially constant current.

7. A method of measuring a resistance of a resistor comprising:
 applying a known voltage across said resistor such that a first current flows through said resistor;
 withdrawing a current equal to said first current from a capacitor having a charge thereon;
 replenishing said charge on said capacitor with a plurality of current pulses, such that one pulse of said plurality is applied to said capacitor when a voltage measured across said capacitor falls below a threshold voltage;
 counting said plurality of pulses over a finite time period; and
 determining a resistance of said resistor based on said counted pulses.

8. The method as in claim 7 further comprising comparing a value of counted pulses to a predetermined value to determine said resistance.

9. The method as in claim 8 wherein when a value of counted pulses is above a reference value, said resistance is determined as having one value and when a value of counted pulses is below said reference value said resistor is determined as having another value.

10. A method of measuring an impedance of a memory element comprising:
 applying a substantially uniform voltage across said memory element;
 flowing a substantially uniform current into said memory element from a charge reservoir;
 flowing a plurality of current pulses into said charge reservoir;
 controlling the flow of said plurality of current pulses in response to a quantity of charge in said charge reservoir;

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counting said plurality of current pulses over a definite time to produce a pulse count; and
 relating an impedance value of said memory element to said pulse count.

11. The method as defined in claim 10 wherein said impedance is an electrical resistance.

12. The method as defined in claim 10 wherein said impedance is a capacitance.

13. The method as defined in claim 10 wherein said impedance is an inductance.

14. A memory integrated circuit comprising:
 a capacitor;
 a resistor;
 a first circuit for conducting current from said capacitor through said resistor;
 a controlled current source for delivering current to said capacitor;
 a comparator for comparing a voltage on said capacitor to a reference voltage and supplying a pulse to turn on said current source when the voltage on said capacitor falls below said reference voltage;
 a pulse counter operatively connected to said comparator output for counting pulses generated by said comparator; and
 a second circuit for determining the value of said resistance based on the value stored in said pulse counter.

15. The memory integrated circuit as defined in claim 14 wherein said comparator further comprises a clock input, the output of said comparator changing state only when a clock signal applied to said clock input changes state.

16. The memory integrated circuit as defined in claim 14 wherein said second circuit is adapted to compare said value stored in said pulse counter to a reference value and determine whether said stored value is greater or less than said reference value.

17. The memory integrated circuit as defined in claim 14 wherein said first circuit further comprises:
 a transistor having a source operatively connected to said capacitor, a gate, and a drain; and
 a differential amplifier having a non-inverting input operatively connected to a first reference voltage, an output operatively connected to said gate, and an inverting input operatively connected to said drain and to said resistor.

18. The memory integrated circuit as defined in claim 14 wherein said second circuit further comprises a digital comparator adapted to receive said value stored in said pulse counter and to receive a reference value, and to compare said stored value to said reference value to produce an output.

19. A resistance measuring circuit comprising:
 a capacitor having a first terminal;
 a voltage controlled current source operatively connected to said first terminal, said current source adapted to withdraw current from said capacitor and supply said current to a resistor to be measured, said voltage controlled current source adapted to control said current according to a voltage measured across said resistor;
 a current pulse generator having an output operatively connected to said first terminal, a clock input adapted to receive a periodic clock signal, and a voltage sensor, said pulse generator adapted to generate a current pulse synchronously with said clock signal whenever said sensor indicates that a voltage at said first terminal is below a threshold voltage, whereby a plurality of current pulses are generated over time;

a first counter adapted to count cycles of said periodic clock signal to produce a clock count;
 a second counter adapted to count pulses produced by said pulse generator to produce a pulse count; and
 a circuit for determining a resistance value of said resistor in response to said pulse count and said clock count.

20. The resistance measuring circuit as in claim 19 wherein said voltage sensor further comprises a clocked comparator.

21. The resistance measuring circuit as in claim 19 wherein said current pulse generator further comprises a current source transistor having a source connected to a supply voltage, a gate, and a drain, a clocked comparator having an inverting input connected to said drain and to said first terminal, a non-inverting input connected to a reference voltage equal to said threshold voltage, an output connected to said gate, and a clock input adapted to receive said clock signal.

22. The resistance measuring circuit as in claim 19 wherein said circuit for determining resistance value further comprises a digital comparator adapted to compare said pulse count to a reference count and produce a first output if said pulse count is above said reference count and a second output if said pulse count is below said reference count.

23. A logic state sensor for a magnetic random access memory cell comprising:

- a controlled voltage supply;
- an electronic charge reservoir;
- a current source;
- a pulse counter;
- said controlled voltage supply operatively connected to a resistive element of a magnetic random access memory device to maintain a substantially constant voltage across said resistive element;

said electronic charge reservoir operatively connected to said controlled voltage supply to provide a current through said resistive element;

said current source operatively connected to said charge reservoir to repeatedly supply a pulse of current to recharge said charge reservoir upon a predetermined depletion of electronic charge from said reservoir;

wherein said pulse counter count is a number of said pulses supplied by said current source over a predetermined time period, the contents of said pulse counter representing a logic state of said memory cell.

24. A processor system comprising:

- a processor and a memory device coupled to said processor, said memory device including a memory cell logic state sensor, said sensor including a controlled voltage supply;
- an electronic charge reservoir;
- a current source;
- a pulse counter;
- said controlled voltage supply operatively connected to a resistive element of a magnetic random access memory device to maintain a substantially constant voltage across said resistive element;
- said electronic charge reservoir operatively connected to said controlled voltage supply to provide a current through said resistive element;
- said current source operatively connected to said charge reservoir to repeatedly supply a pulse of current to recharge said charge reservoir upon a predetermined depletion of electronic charge from said reservoir;
- wherein said pulse counter count is a number of said pulses supplied by said current source over a predetermined time period, the contents of said pulse counter representing a logic state of said memory cell.

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